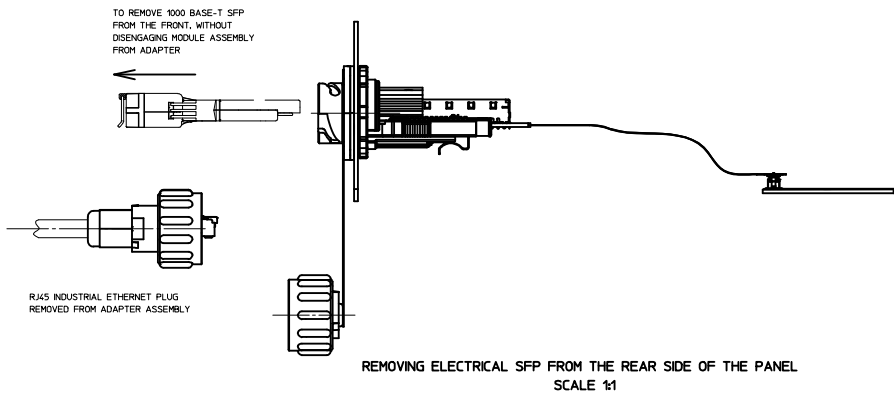


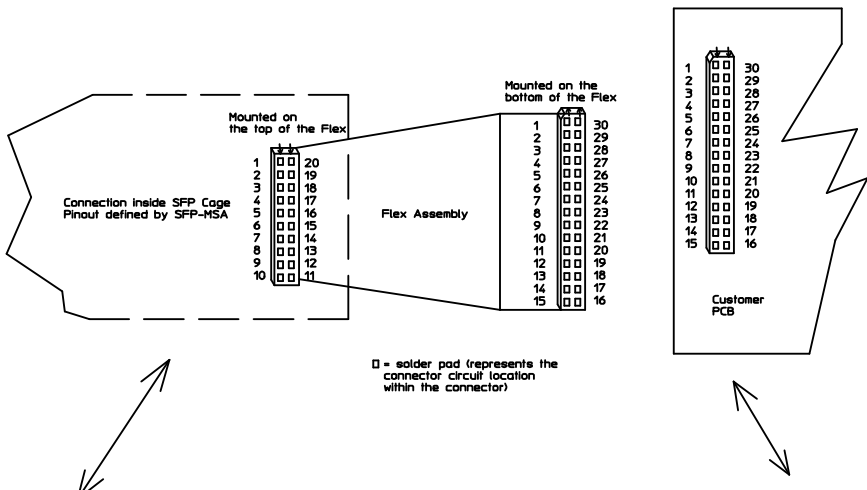
NOTE:  
ALL DIMENSIONS ARE FOR REFERENCE ONLY.



<b>ENTER DESCRIPTION</b> IEC NO: MF2010-0779 DRAWN: SADAUSK/ENE 2009/10/22 CHKD: 2009/10/23 APPR: BANDRELL 2009/10/23	QUALITY SYMBOLS ▽=0 ▽=0	GENERAL TOLERANCES (UNLESS SPECIFIED) <table border="1"> <thead> <tr> <th></th> <th>mm</th> <th>INCH</th> </tr> </thead> <tbody> <tr> <td>4 PLACES</td> <td>±---</td> <td>±---</td> </tr> <tr> <td>3 PLACES</td> <td>±---</td> <td>±---</td> </tr> <tr> <td>2 PLACES</td> <td>±---</td> <td>±---</td> </tr> <tr> <td>1 PLACE</td> <td>±---</td> <td>±---</td> </tr> </tbody> </table> ANGULAR ±1/2°		mm	INCH	4 PLACES	±---	±---	3 PLACES	±---	±---	2 PLACES	±---	±---	1 PLACE	±---	±---	DIMENSION STYLE <b>MM ONLY</b>	SCALE <b>2:1</b>	DESIGN UNITS <b>METRIC</b>	THIRD ANGLE PROJECTION
		mm	INCH																		
	4 PLACES	±---	±---																		
	3 PLACES	±---	±---																		
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1 PLACE	±---	±---																			
DRAWN BY BG	DATE 12/01/05	CHECKED BY SE	DATE 12/15/05	MATERIAL NO. <b>1065012000</b>	DOCUMENT NO. <b>SD-106501-2000</b>	TITLE <b>INDUSTRIAL ELECT'R'L SFP MODULE ASSEMBLY</b>															
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		APPROVED BY DATE		MOLEX INCORPORATED																	
SIZE <b>D</b>			THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION																		

Pin #	Name	Function	Plug Sequence (from SFP)	Notes
1	VeeT	Transmitter Ground	1	Note 6
2	TD+	Inv. Transmitter Data In	3	Note 9
3	VeeT	Transmitter Ground	1	Note 6
4	TD+	Transmitter Data In	3	Note 9
5	VeeT	Transmitter Ground	1	Note 6
6	VccT	Transmitter Power	2	3.3 ± 5%, Note 8
7	Ground	Ground		
8	Ground	Ground		
9	Ground	Ground		
10	VccR	Receiver Power	2	3.3 ± 5%, Note 8
11	VeeR	Receiver Ground	1	Note 6
12	RD+	Received Data Out	3	Note 7
13	VeeR	Receiver Ground	1	Note 6
14	RD+	Inv. Received Data Out	3	Note 7
15	VeeR	Receiver Ground	1	Note 6
16	VeeR	Receiver Ground	1	Note 6
17	VeeR	Receiver Ground	1	Note 6
18	LOS	Loss of Signal	3	Note 5
19	Rate Select	Full or reduced receiver bandwidth	3	Note 4, Low or Open - Reduced Bandwidth, High - Full Bandwidth
20	Ground	Ground		
21	Ground	Ground		
22	Ground	Ground		
23	Ground	Ground		
24	VeeC	Clock Ground	1	Note 6
25	MOD-DEF0	Module Definition 0 (Ground)	3	Note 3, grounded in module
26	MOD-DEF1	Module Definition 1 (Clock)	3	Note 3, 2 wire serial ID interface
27	MOD-DEF2	Module Definition 2 (Data)	3	Note 3, 2 wire serial ID interface
28	TX Disable	Transmitter Disable	3	Note 2, module disables on high or open
29	TX Fault	Transmitter Fault Indication	3	Note 1
30	VeeT	Transmitter Ground	1	Note 6

Industrial SFP Circuit Wiring Scheme



NOTES:

- Plug Sequence = Pin engagement sequence during hot plugging of SFP Module.
- 1) TX Fault is an open collector/drain output, which should be pulled up with a 4.7K - 10K W resistor on the host board. Pull up voltage between 2.0V and VccT, R=0.3V. When high, output indicates a laser fault of some kind, Low indicates normal operation. In the low state, the output will be pulled to < 0.8V.
- 2) TX Disable is an input that is used to shut down the transmitter optical output. It is pulled up within the module with a 4.7 - 10 K W resistor. Its states are:  
 Low (0 - 0.8V): Transmitter on  
 (0.8 - 2.0V): Undefined  
 High (2.0 - 3.45V): Transmitter Disabled  
 Open: Transmitter Disabled
- 3) Mod-Def 0,1,2. These are the module definition pins. They should be pulled up with a 4.7K - 10K W resistor on the host board. The pull-up voltage shall be VccT or VccR (see Section IV for further details).  
 Mod-Def 0 is grounded by the module to indicate that the module is present  
 Mod-Def 1 is the clock line of two wire serial interface for serial ID  
 Mod-Def 2 is the data line of two wire serial interface for serial ID
- 4) This is an optional input used to control the receiver bandwidth for compatibility with multiple data rates (most likely Fibre Channel 1x and 2x Rates). If implemented, the input will be internally pulled down with > 30k W resistor. The input states are:  
 Low (0 - 0.8V): Reduced Bandwidth  
 (0.8 - 2.0V): Undefined  
 High (2.0 - 3.45V): Full Bandwidth  
 Open: Reduced Bandwidth
- 5) LOS (Loss of Signal) is an open collector/drain output, which should be pulled up with a 4.7K - 10K W resistor. Pull up voltage between 2.0V and VccT, R=0.3V. When high, this output indicates the received optical power is below the worst-case receiver sensitivity (as defined by the standard in use). Low indicates normal operation. In the low state, the output will be pulled to < 0.8V.
- 6) VeeR, VeeT, and VeeC may be internally connected within the SFP module.
- 7) RD+/-: These are the differential receiver outputs. They are AC coupled 100 W differential lines which should be terminated with 100 W (differential) of the user SERDES. The AC coupling is done inside the module and is thus not required on the host board. The voltage swing on these lines will be between 370 and 2000 mV differential (185 - 1000 mV single ended) when properly terminated.
- 8) VccR and VccT are the receiver and transmitter power supplies. They are defined as 3.3V ± 5% of the SFP connector pin. Maximum supply current is 300 mA. Inductors with DC resistance of less than 1 W should be used in order to maintain the required voltage at the SFP input pin with 3.3V supply voltage. When the recommended supply filtering network is used, hot plugging of the SFP transceiver module will result in an inrush current of no more than 30 mA greater than the steady state value. VccR and VccT may be internally connected within the SFP transceiver module. Each Vcc will be individually filtered near the SFP connector.
- 9) TD+/-: These are the differential transmitter inputs. They are AC-coupled, differential lines with 100 W differential termination inside the module. The AC coupling is done inside the module and is thus not required on the host board. The inputs will accept differential swings of 500 - 2400 mV (250 - 1200 mV single-ended), though it is recommended that values between 500 and 1200 mV differential (250 - 600 mV single-ended) be used for best EM performance.

SFP Pinout

1 (key)	VeeT	VeeT	20
2	TXFault	TD-	19
3	TX Disable	TD+	18
4	MOD-DEF(2)	VeeT	17
5	MOD-DEF(1)	VccT	16
6	MOD-DEF(0)	VccR	15
7	Rate Select	VeeR	14
8	LOS	RD+	13
9	VeeR	RD-	12
10	VeeR	VeeR	11

Connector wiring on Customers PCB

1 (key)	VeeT (ground)	VeeT (ground)	30
2	TD-	TXFault	29
3	VeeT (ground)	TX Disable	28
4	TD+	MOD-DEF(2)	27
5	VeeT (ground)	MOD-DEF(1)	26
6	VccT	MOD-DEF(0)	25
7	Ground	VeeC (ground)	24
8	Ground	Ground	23
9	Ground	Ground	22
10	VccR	Ground	21
11	VeeR (ground)	Ground	20
12	RD+	Rate Select	19
13	VeeR (ground)	LOS	18
14	RD-	VeeR (ground)	17
15	VeeR (ground)	VeeR (ground)	16

<b>ENTER DESCRIPTION</b> EC NO: MF2010-0179 DRAWN: SADAUSV/ENE 2009/10/22 CHKD: 2009/10/23 APPR: BANDRELL 2009/10/23 REV: DESCRIPTION	QUALITY SYMBOLS ▽=0 ▽=0	GENERAL TOLERANCES (UNLESS SPECIFIED) mm INCH 4 PLACES ± --- ± --- 3 PLACES ± --- ± --- 2 PLACES ± --- ± --- 1 PLACE ± --- ± --- ANGULAR ±1/2°	DIMENSION STYLE MM ONLY	SCALE DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
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	APPROVED BY DATE	MOLEX INCORPORATED	DOCUMENT NO. SD-106501-2000	SHEET NO. 2 OF 2	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION	
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	SIZE D				